

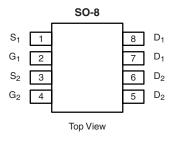
Dual N-Channel 20-V (D-S) MOSFET

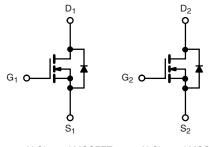
PRODUCT SUMMARY				
V _{DS} (V)	V _{DS} (V) R _{DS(on)} (Ω)			
20	0.019 at V _{GS} = 4.5 V	7.1		
	0.026 at V_{GS} = 2.5 V	6.0		

FEATURES

- Halogen-free According to IEC 61249-2-21
 Definition
- TrenchFET[®] Power MOSFET
- 100 % R_g Tested
- Compliant to RoHS Directive 2002/95/EC







N-Channel MOSFET

N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS $T_A = 25 \text{ °C}$, unless otherwise noted					
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	20	V	
Gate-Source Voltage		V _{GS}	± 12	- V	
	T _A = 25 °C	1	7.1		
Continuous Drain Current (T _J = 150 °C) ^a	T _A = 70 °C	I _D	5.7	_	
Pulsed Drain Current (10 µs Pulse Width)		I _{DM}	40	— A	
Continuous Source Current (Diode Conduction) ^a		۱ _S	1.7		
	T _A = 25 °C	P _D	2	w	
Maximum Power Dissipation ^a	T _A = 70 °C	'D	1.3		
Operating Junction and Storage Temperature Rang	je	T _J , T _{stg}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS					
Parameter	Symbol	Limit	Unit		
Maximum Junction-to-Ambient ^a	R _{thJA}	62.5	°C/W		

Notes:

a. Surface Mounted on FR4 board, t \leq 10 s.

SPECIFICATIONS T _J = 25 °C, unless otherwise noted							
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static					-	-	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	0.6		1.5	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 12 V$			± 100	nA	
Zero Gate Voltage Drain Current	lass	$V_{DS} = 20 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			1	μA	
Zero Gale voltage Drain Gurrent	IDSS	$V_{DS} = 20 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 55 \text{ °C}$			5		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5$ V, $V_{GS} = 4.5$ V	20			А	
	P	$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 7.1 \text{ A}$		0.019		0	
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 2.5 \text{ V}, \text{ I}_{D} = 6.0 \text{ A}$		0.026		Ω	
Forward Transconductance ^a	9 _{fs}	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 7.1 \text{ A}$		27		S	
Diode Forward Voltage ^a	V _{SD}	$I_{S} = 1.7 \text{ A}, V_{GS} = 0 \text{ V}$			1.2	V	
Dynamic ^b						•	
Total Gate Charge	Qg			9.5			
Gate-Source Charge	Q _{gs}	V_{DS} = 10 V, V_{GS} = 4.5 V, I_{D} = 7.1 A		1.5		nC	
Gate-Drain Charge	Q _{gd}			2.5		1	
Gate Resistance	Rg	f = 1 MHz		1.6	2.7	Ω	
Turn-On Delay Time	t _{d(on)}			10			
Rise Time	tr	V_{DD} = 10 V, R_L = 10 Ω		15			
Turn-Off Delay Time	t _{d(off)}	$I_D \cong$ 1 A, V_{GEN} = 4.5 V, R_g = 10 Ω		38		ns	
Fall Time	t _f			25		1	
Source-Drain Reverse Recovery Time	t _{rr}	I _F = 1.7 A, dl/dt = 100 A/μs		26			

Notes:

a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



T_C = 125 °C

1.5

V_{GS} - Gate-to-Source Voltage (V)

Transfer Characteristics

55 °C

2.5

3.0

2.0

25 °C

1.0

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Coss

8

V_{DS} - Drain-to-Source Voltage (V)

Capacitance

12

16

20

4

0

25

50

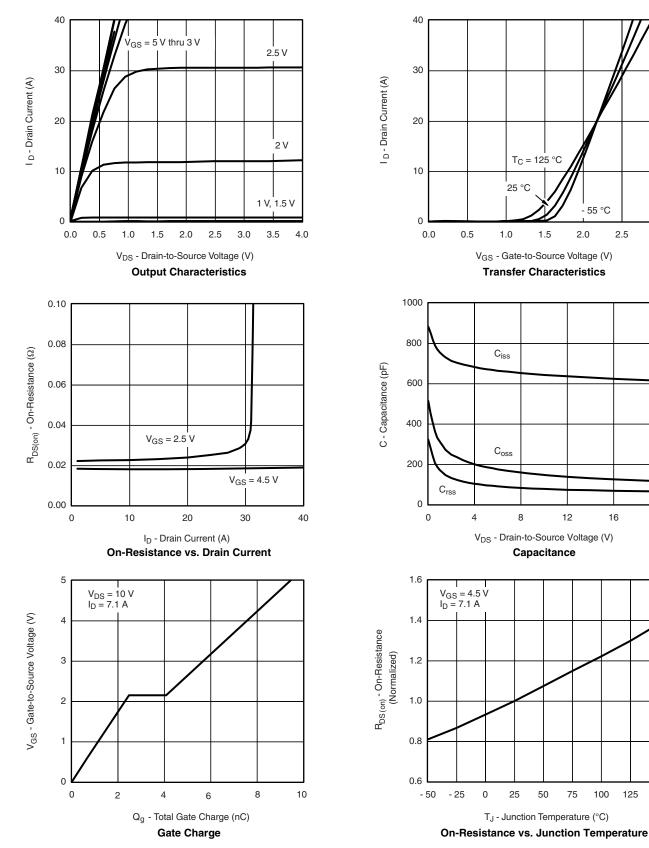
T_J - Junction Temperature (°C)

75

100

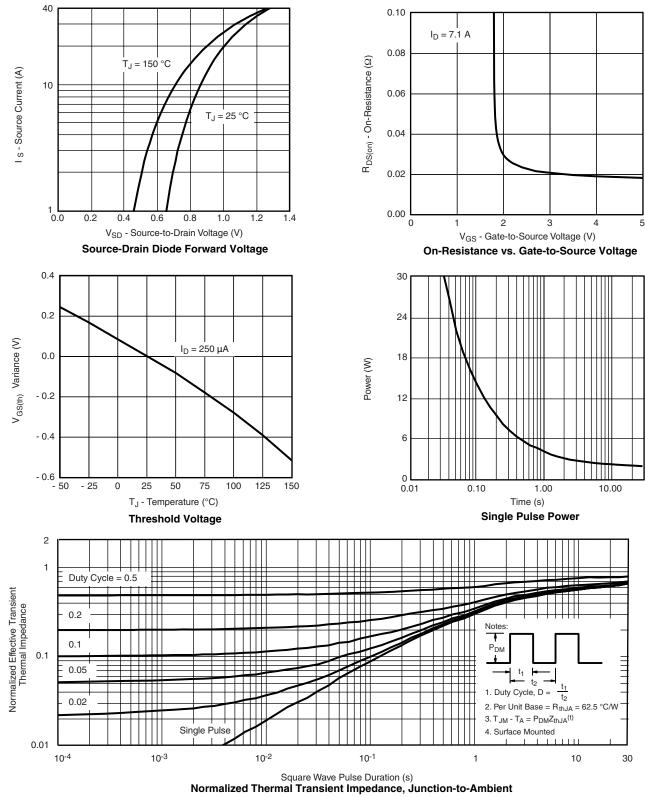
125 150

0.5



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





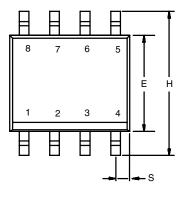
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

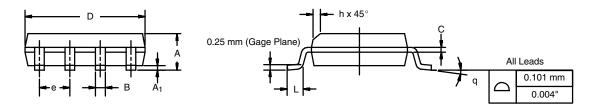




SOIC (NARROW): 8-LEAD

JEDEC Part Number: MS-012

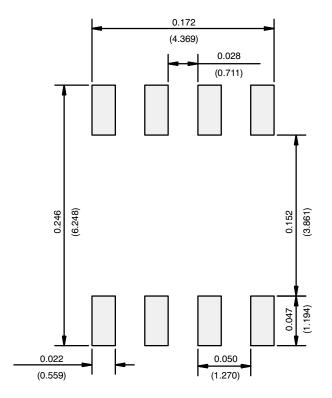




	MILLIM	IETERS	INC	HES	
DIM	Min	Мах	Min	Max	
A	1.35	1.75	0.053	0.069	
A ₁	0.10	0.20	0.004	0.008	
В	0.35	0.51	0.014	0.020	
С	0.19	0.25	0.0075	0.010	
D	4.80	5.00	0.189	0.196	
E	3.80	4.00	0.150	0.157	
е	1.27	BSC	0.050 BSC		
н	5.80	6.20	0.228	0.244	
h	0.25	0.50	0.010	0.020	
L	0.50	0.93	0.020	0.037	
q	0°	8°	0°	8°	
S	0.44	0.64	0.018	0.026	
ECN: C-06527-Rev. I, 11-Sep-06 DWG: 5498					



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)



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